

WHAT IS CLAIMED IS:

1. A wafer mapping apparatus for determining whether a wafer is present or not on each of shelves when a pod having a box which has an opening and the shelves
5 for taking custody of the wafer in parallel along a vertical direction and a lid separably covering said opening is fixed to a wafer processing apparatus, said wafer mapping apparatus comprising:

a first sensor for determining whether the wafer is present or not on shelves;
a mapping frame for supporting said first sensor; a movable portion for
10 supporting said first sensor movable in the vertical direction through said mapping frame in a state in which said sensor is plunged into said box;
a timing plate having index means disposed at predetermined intervals; and
second sensors provided so as to sandwich said index means therebetween,
wherein a signal in response to each of said shelves is generated by said timing
15 plate and said second sensor in accordance with a vertical movement of said sensor.

2. A wafer mapping apparatus according to claim 1, wherein said movable portion and said second sensors are located underside of lower edge of said opening, and are provided within a substantially closed space.

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3. A wafer mapping apparatus according to claim 1, wherein said movable portion is connected with a door which holds said lid of said pod, apart said lid from said box, and moves said lid substantially below said box.

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4. A wafer mapping apparatus according to claim 2, wherein said movable portion is connected with a door which holds said lid of said pod, apart said lid from said box, and moves said lid substantially below said box.

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5. A wafer mapping apparatus according to claim 1, wherein said mapping frame is tilted so that the upper side thereof is apart from a plane forming said opening of said pod in a state that said opening is closed by said lid, and said sensor is plunged into said box after said opening is opened.

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6. A wafer mapping apparatus according to claim 2, wherein said mapping frame is tilted so that the upper side thereof is apart from a plane forming said opening of said pod in a state that said opening is closed by said lid, and said sensor is plunged into said box after said opening is opened.

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7. A wafer mapping apparatus according to claim 3, wherein said mapping frame is tilted so that the upper side thereof is apart from a plane forming said opening of said pod in a state that said opening is closed by said lid, and said sensor is plunged into said box after said opening is opened.